KEY SERVICES
• Wafer probe
• Wafer Backgrinding
• Assembly of Leadframe, Array and Leadless packages
• Final Test
• Tape and Reel
• Drop Shipping and Distribution

KEY FACTS
• Factory Floor Space Services: 409,000 ft² (38,000 m²)
• Equipment Capacity: 5 million units/capacity a day
• Employees: 1,500

SUPPLIER AWARDS
• On Semi, Freescale, EXAR, Delphi, Elmos, Infineon, Zilog, IDT, Zarlink

TEST PLATFORMS
• Linear/Analog
• High-end RF
• Mixed Signal
• VLSI

PACKAGE PORTFOLIO
• Array Packages - FBGA, LGA
• Leadframe Packages - TSSOP, SSOP, QSOP, QFP, LQFP, TQFP, PLCC, SOIC, PDIP
• Leadless Packages - DFN/QFN
• MEMS Packaging

CERTIFICATIONS
• ISO 14001:2004
• ISO 9001:2008
• ISO/TS 16949:2009
• Certificate of Green Partner (Sony)